



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20210427002.1
Qualify TI Malaysia as an additional Assembly site for Select Devices
Change Notification / Sample Request

Date: May 11, 2021
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20210427002.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM2674M-ADJ/NOPB	null
LM2675M-3.3/NOPB	null
LM2675M-ADJ/NOPB	null
LM2901M/NOPB	null
LP2951CM-3.3/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20210427002.1		PCN Date:	May 11, 2021																					
Title:	Qualify TI Malaysia as an additional Assembly site for Select Devices																								
Customer Contact:	PCN Manager	Dept:	Quality Services																						
Proposed 1st Ship Date:	Aug. 11, 2021		Estimated Sample Availability:	Date provided at sample request																					
Change Type:																									
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site																				
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material																				
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process																				
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site																				
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials																				
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process																				
PCN Details																									
Description of Change:																									
Texas Instruments is pleased to announce the qualification of TI Malaysia as an Additional Assembly site for the list of devices shown below. Current assembly site and Material differences are as follows:																									
<table border="1"> <thead> <tr> <th></th> <th>TIEM</th> <th>AP1</th> <th>MLA</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>8075531</td> <td>SID#101375281</td> <td>4147858</td> </tr> <tr> <td>Mold Compound</td> <td>8096859</td> <td>SID#101323397</td> <td>4211880</td> </tr> <tr> <td>Lead Finish</td> <td>Matte Sn</td> <td>Matte Sn</td> <td>NiPdAu</td> </tr> <tr> <td>##Bond wire, diameter</td> <td>Au, 1.3 mils</td> <td>Au, 1.3 mils</td> <td>Cu, 1.3 mils</td> </tr> </tbody> </table>							TIEM	AP1	MLA	Mount Compound	8075531	SID#101375281	4147858	Mold Compound	8096859	SID#101323397	4211880	Lead Finish	Matte Sn	Matte Sn	NiPdAu	##Bond wire, diameter	Au, 1.3 mils	Au, 1.3 mils	Cu, 1.3 mils
	TIEM	AP1	MLA																						
Mount Compound	8075531	SID#101375281	4147858																						
Mold Compound	8096859	SID#101323397	4211880																						
Lead Finish	Matte Sn	Matte Sn	NiPdAu																						
##Bond wire, diameter	Au, 1.3 mils	Au, 1.3 mils	Cu, 1.3 mils																						
## - Applies to only the LM2674M-5.0/NOPB																									
NOTE: Devices are currently built at either TIEM or AP1 or both																									
Upon expiry of this PCN TI will combine lead free solutions in a single standard part number , for this device. For example; LM2901M/NOPB – can ship with both Matte Sn and NiPdAu.																									
Example:																									
<ul style="list-style-type: none"> - Customer order for 7500 units of LM2901M/NOPB with 2500 units SPQ (Standard Pack Quantity per Reel). - TI can satisfy the above order in one of the following ways. <ul style="list-style-type: none"> I. 3 Reels of NiPdAu finish. II. 3 Reels of Matte Sn finish III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish. IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish. 																									
Reason for Change:																									
Continuity of Supply																									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																									
None																									
Anticipated impact on Material Declaration																									
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp																						

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TIEM	CU6	MYS	Kuala Lumpur
AP1	AKR	PHL	Cupang, Muntinlupa City
TI Malaysia	MLA	MYS	Ayutthaya

Sample product shipping label (not actual product label)

G3: Matte Sn
G4: NiPdAu

Product Affected:

LM2674M-12/NOPB	LM2675MX-ADJ/J7002911	LM5101AMX/NOPB	LMV844MAX/NOPB
LM2674M-3.3/NOPB	LM2675MX-ADJ/NOPB	LM5101AMX/S7003027	LP2951ACM-3.0/NOPB
LM2674M-5.0/NOPB	LM2901M/NOPB	LM5101BMA/NOPB	LP2951ACM-3.3/NOPB
LM2674M-ADJ/NOPB	LM2901MX/NOPB	LM5101BMAX/NOPB	LP2951ACM/NOPB
LM2674MX-12/NOPB	LM2902M/NOPB	LM5101CMA/NOPB	LP2951ACMX-3.0/NOPB
LM2674MX-3.3/NOPB	LM2902MX/E7002681	LM5101CMAX/NOPB	LP2951ACMX-3.3/NOPB
LM2674MX-5.0/NOPB	LM2902MX/NAK2	LM5101M/NOPB	LP2951ACMX/NOPB
LM2674MX-ADJ/NOPB	LM2902MX/NOPB	LM5101MX/NOPB	LP2951CM-3.0/NOPB
LM2675M-12/NOPB	LM324AM/NOPB	LM5109AMA/NOPB	LP2951CM-3.3/NOPB
LM2675M-3.3/NOPB	LM324AMX/NOPB	LM5109AMAX/NOPB	LP2951CM/NOPB
LM2675M-5.0/NOPB	LM324M/NOPB	LM5109BMA/NOPB	LP2951CMX-3.0/NOPB
LM2675M-ADJ/NOPB	LM324MX/NOPB	LM5109BMAX/NOPB	LP2951CMX-3.3/NOPB
LM2675MX-12/NOPB	LM339AM/NOPB	LM5109MA/NOPB	LP2951CMX/E7002608
LM2675MX-3.3/E7002948	LM339AMX/NOPB	LM5109MAX/NOPB	LP2951CMX/J7000697
LM2675MX-3.3/NAK2	LM339M/NOPB	LMV324M/NOPB	LP2951CMX/NAK2
LM2675MX-3.3/NOPB	LM339MX/NOPB	LMV324MX/NOPB	LP2951CMX/NOPB
LM2675MX-5.0/NOPB	LM5101AM/NOPB	LMV844MA/NOPB	

Qualification Report

Approve Date 16-Feb-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM2675MXADHHC NC	Qual Device: LM5101AMXSF0 S4	Qual Device: LMV844MAX/NO PB	QBS Package Reference: CD4081BM96	QBS Package Reference: LM393DR ROUG H.LDF	QBS Package Reference: LP2951ACMX- 3.3/S2	QBS Package Reference: TCA9546ADR.R LE
AC	Autoclave 121C	96 Hours	3/231/0	-	3/231/0	3/228/0	3/231/0	1/77/0	3/231/0
ED	Auto Electrical Distributions	Cpk>1.67 Room, hot, and cold test	-	-	-	-	-	1/30/0	-
ED	Electrical Characterization, side by side	-	1/30/0	1/30/0	1/30/0	-	-	-	-
FLAM	Flammability (UL 94V-0)	-	-	-	-	-	-	-	3/15/0
HAST	Biased HAST, 130C/85%RH	192 Hours (for info)	-	-	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	-	1/77/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	3/231/0	-	3/231/0
LI	Lead Fatigue	Leads	-	-	-	3/66/0	3/66/0	-	-
LI	Lead Pull	Leads	-	-	-	3/126/0	3/72/0	-	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	3/90/0	1/30/0	-
SD	Solderability	Pb Free	-	-	-	3/66/0	-	-	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-	3/231/0	3/231/0	3/231/0	1/77/0	3/231/0
VM	Visual / Mechanical	-	3/984/0	3/984/0	3/984/0	3/984/0	3/984/0	3/984/0	3/984/0
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/90/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/90/0	3/228/0

- QBS: Qual By Similarity
- Qual Devices LM2675MXADHHC, LM5101AMXSF0S4 and LMV844MAX/NOPB are qualified at LEVEL-1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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